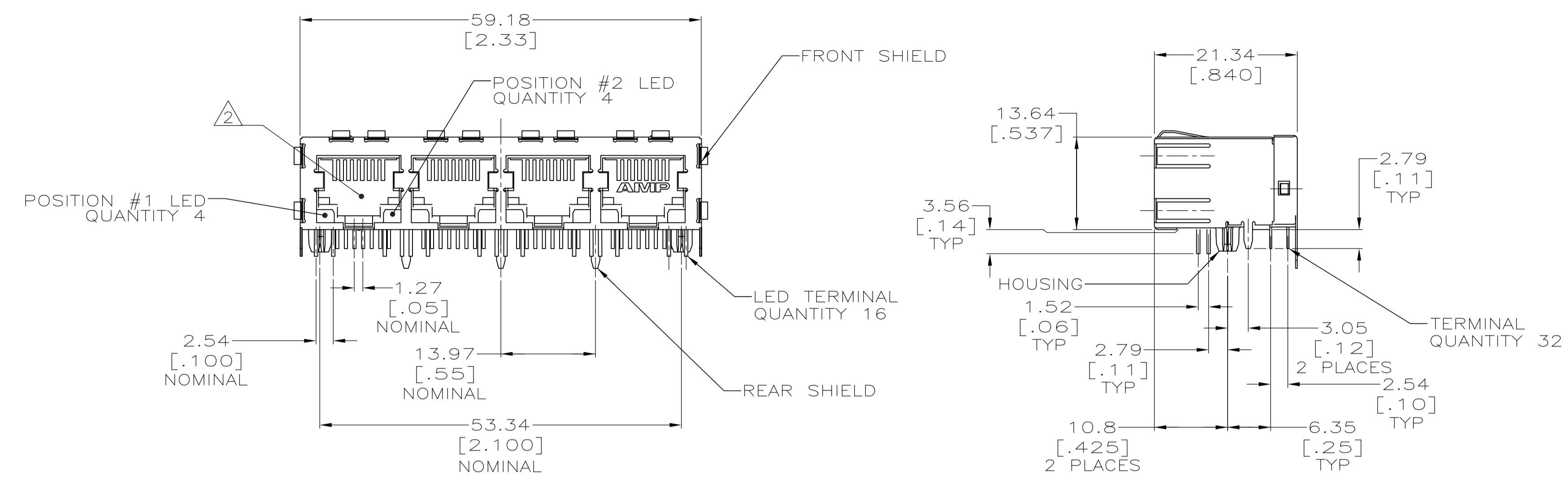
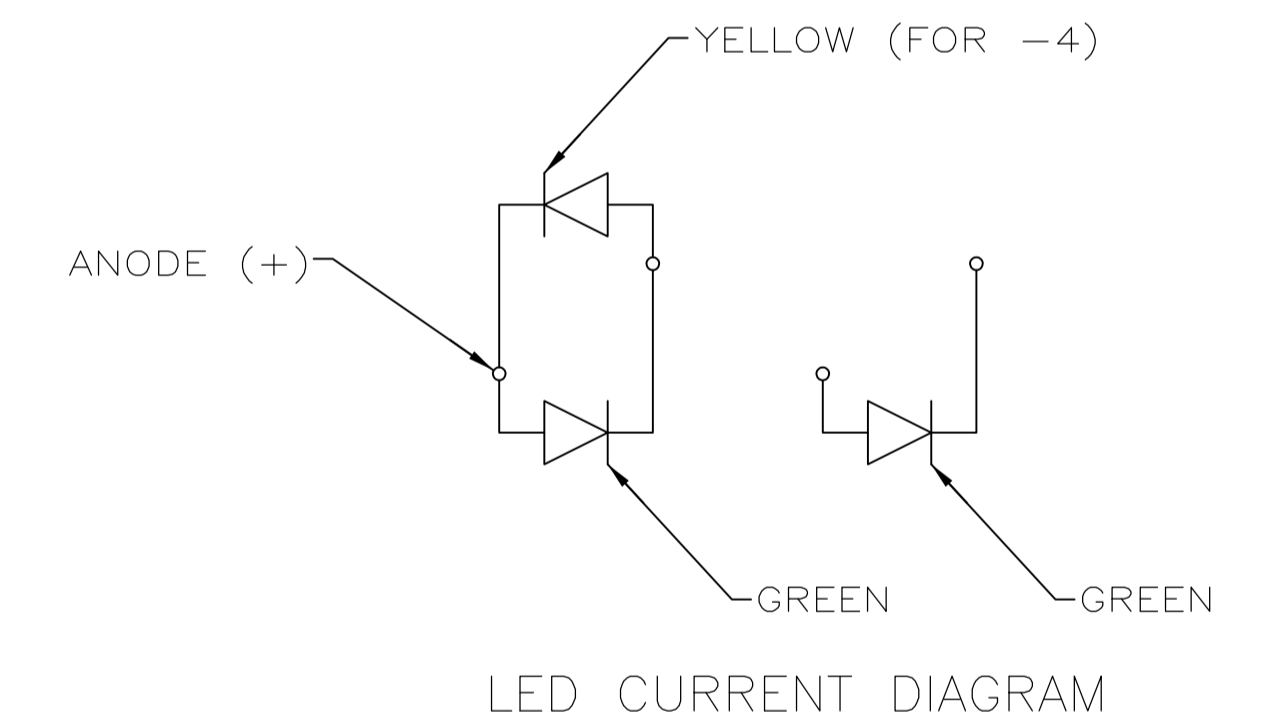
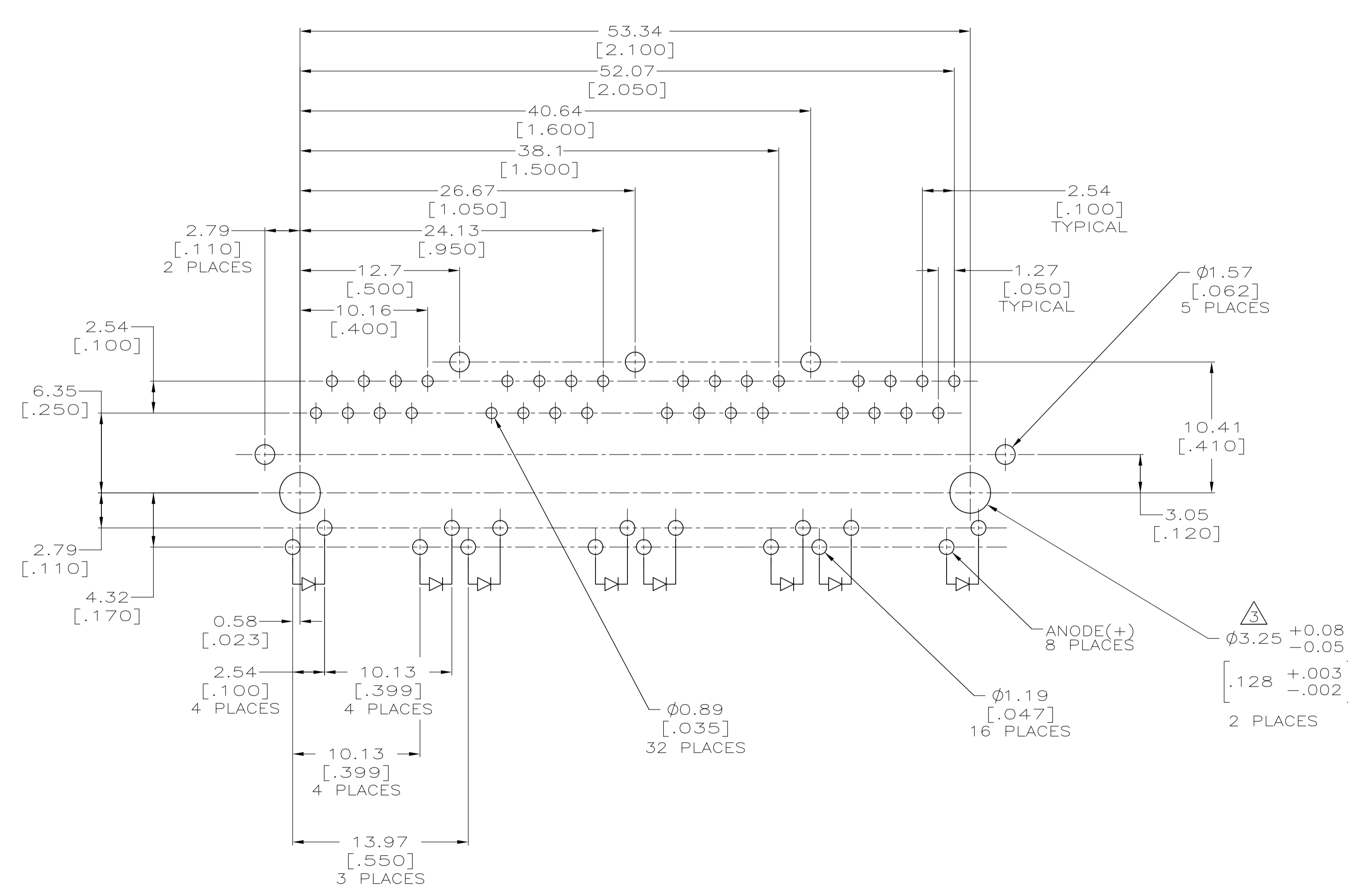


LOC		DIST		REVISIONS			
F	LTR	DESCRIPTION	DATE	DN	APVD		
B		REV PER ECR-08-032447	23FEB2009	DZ	SY		
B1		REVISED PER ECO-10-000444	19JAN10	KK	HMR		



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27 $\mu$ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 $\mu$ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 $\mu$ m[.000050] MINIMUM THICK NICKEL UNDERPLATE.  
 SHIELD - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27 $\mu$ m[.000050] MINIMUM NICKEL AND 2.03 $\mu$ m[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 $\mu$ m[.0003500] THICK Sn/Cu OVER 2.03 $\mu$ m[.000080] THICK Ag OVER 1.02 $\mu$ m[.000040] THICK Cu OVER 3.56 $\mu$ m[.000140] THICK Ni OVER 1.02 $\mu$ m[.000040] Cu UNDERPLATE
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PRINTED CIRCUIT BOARD HOLES.
- 4 THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- 5 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SUGGESTED PC BOARD LAYOUT  
 COMPONENT SIDE  
 SCALE 4:1

LED POSN#1(LEFT)	LED POSN#2(RIGHT)	PART NUMBER
GREEN/YELLOW	GREEN	6116125-4
GREEN	GREEN	<del>6116125-2</del>
GREEN	YELLOW	6116125-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		Tyco Electronics Corporation	
DIMENSIONS: mm[inches]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	Tyco Electronics Corporation	
0 PLC ± -	1 PLC ± -	Harrisburg, PA 17105-3608	
2 PLC ± 0.25[.01]	3 PLC ± 0.13[.005]	MODULAR JACK ASSEMBLY, 4 PORT, 8 POSITION, RIGHT ANGLE, PANEL GROUND WITH LED	
4 PLC ± -	ANGLES ± -	SIZE	CAGE CODE DRAWING NO
MATERIAL	FINISH	A1	00779
CUSTOMER DRAWING		SCALE	2:1
		SHEET	1 OF 1
		REV	B1